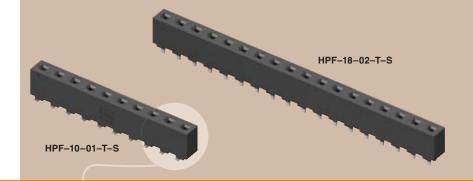


(5,08mm) .200" HPF SERIES



POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material: Black LCP Contact Material: BeCu

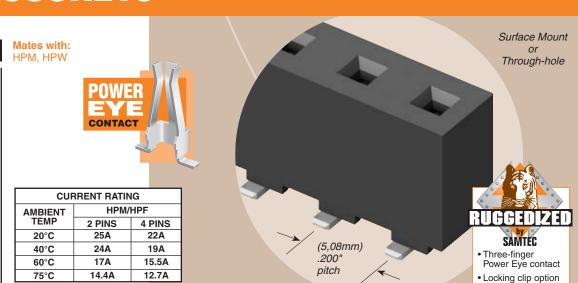
Plating: Sn over 50μ" (1,27μm) Ni Insertion Depth: (3,68mm) .145" to (8,26mm) .325" (.368" (9,35mm) plus board thickness minimum for

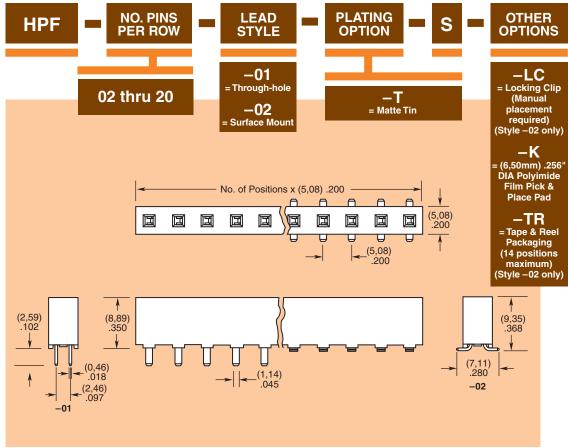
bottom entry)
Wiping Distance:
(0,38mm) .015" Insertion Force:

(Single contact only) 56oz (15,57N) avg. Withdrawal Force: (Single contact only) 52oz (14,46N) avg. Lead-Free Solderable:

SMT Lead Coplanarity:

(0,15mm) .006" max (02-10) (0,20mm) .008" max (11-20) **RoHS Compliant:**





Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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